

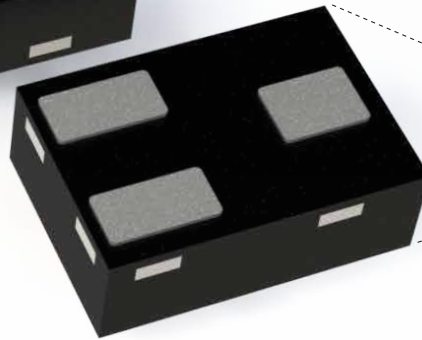
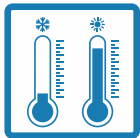
Robust, reliable, small



MicroSON[®]-3 SMD package

with NXP UCODE[®] 8 and UCODE[®] 8m

For industrial UHF RFID applications under harsh conditions



Designed for industrial applications

KEY BENEFITS

- Reliable performance under harsh conditions
- Moisture Sensitivity Level 1 (MSL-1) qualified
- Tailored to fit industrial application requirements
- Featuring UHF Gen2v2 RFID chip NXP UCODE[®] 8 and UCODE[®] 8m



TARGET APPLICATIONS

- Ruggedized tag design
- PCB tagging, tracking & tracing
- Asset management with high reliability requirements
- Industrial work in progress tracking

KEY FEATURES

- Plastic extremely thin small outline package
- No-leads, 3 terminals
- Size 1.45 x 1.00 x 0.5 mm
- For surface-mount assembly
- Industrial (operating) temperature -40°C to +85°C
- Storage temperature package -55°C to +125°C




MicroSON®-3 SMD package

For industrial UHF RFID applications under harsh conditions

MicroSON®-3 RFID SMD package is a Small Outline No-leads (SON) package. It is available with the UHF Gen2v2 (RAIN) compliant RFID chips from NXP, the UCODE® 8 and the UCODE® 8m. MicroSON®-3 is a near chip scale plastic

encapsulated package with a copper leadframe substrate. It is a leadless package where electrical contact to the PCB is made by soldering the terminals on the bottom surface of the package to the PCB, instead of the conventional formed perimeter leads.

PRODUCT FEATURES

Product	MicroSON®-3 NXP UCODE® 8	MicroSON®-3 NXP UCODE® 8m
Product code	SON-A1AU8NAZ1	SON-A1AUmNAZ1
RAIN RFID IC (chip)	NXP UCODE® 8	NXP UCODE® 8m
Appearance		
Size	1.45 x 1.00 x 0.5 mm	1.45 x 1.00 x 0.5 mm
Industrial (operating) temperature IC	-40°C to +85°C	-40°C to +85°C
Storage temperature package	-55°C to +125°C	-55°C to +125°C
Frequency	UHF (860-960MHz)	UHF (860-960MHz)
Standards	EPCglobal and ISO 18000-63 	EPCglobal and ISO 18000-63 
Antenna	External required	External required
TID Memory	96 bits	96 bits
Memory configuration	128 bit EPC + 0 bit UM	96 bit EPC + 32 bit UM
Storage temperature IC	-55°C to +125°C	-55°C to +125°C



ADDITIONAL INFORMATION

Detailed package information including drawings can be found in the MicroSON®-3 product specifications and data sheets, available through our website. Interested in MicroSON®-3?

Contact us for additional information such as samples, pricing and lead times. Please provide us with the details of your chip if you want to find out if we have a suitable package solution for you.

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